



Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays

Marketing Name / Model

[List multiple models if applicable.]

HP W2271d 21.5-inch LED Backlit LCD Monitor

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Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		2
External electrical cables and cords		2
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Screw driver of "+" type	200mm
Description #2 Hexagonal nut screw driver for DVI and D-SUB connector	200mm
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Dismantle the screws of rear cover;
2. Dismantle the stand & base of monitor;
3. Dismantle the cover of monitor;
4. Dismantle the button, pull out the pin of KEPC board ,get down the KEPC board;
5. Dismantle BEZEL;
6. Pull out the PIN of lamp;
7. Pull out the PIN of LVDS cable, separate the mainframe and PANEL;
8. Dismantle mainframe;
9. Dismantle the power board screws;
10. Dismantle the VGA and DVI screws;
11. First: Tear off the adhesive tape;
12. Second: Pull out the connector PIN which connect PWPC and main board;
13. Third: Take off both boards;
14. Pull out the pin of KEPC cable;
- 15.
- 16.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).



HP 21.5 Disassembly Process





External Electric Cables Dissecting Process



1.Remove Cable From Display Head.



2.Dissecting to Complete.



Remove Stand Base From Display



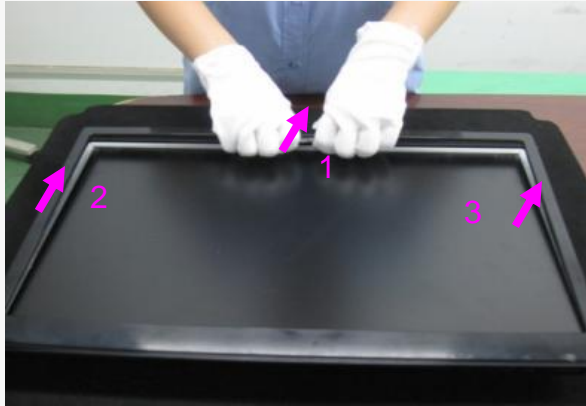
1. Take Screw(*5) from Rear Cover.



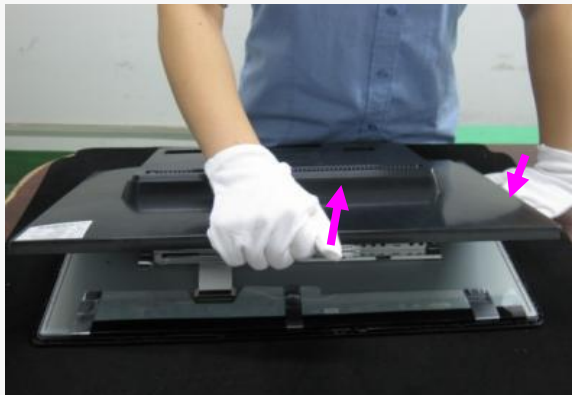
2. Demount Stand & Remove Stand Base Form Display.



Remove Rear Cover From Display Head



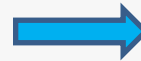
1. Both Hands Upwardly Pull Up.



3. Toward the arrowhead , take the Rear Cover from the Front Cover.



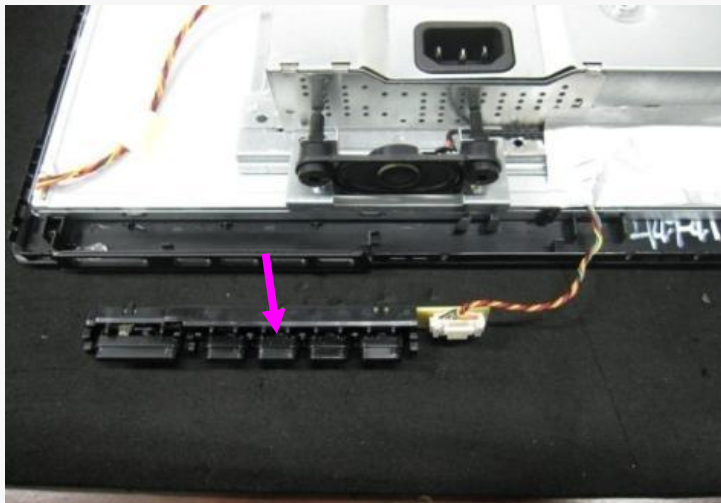
2. Turn over Display Head.



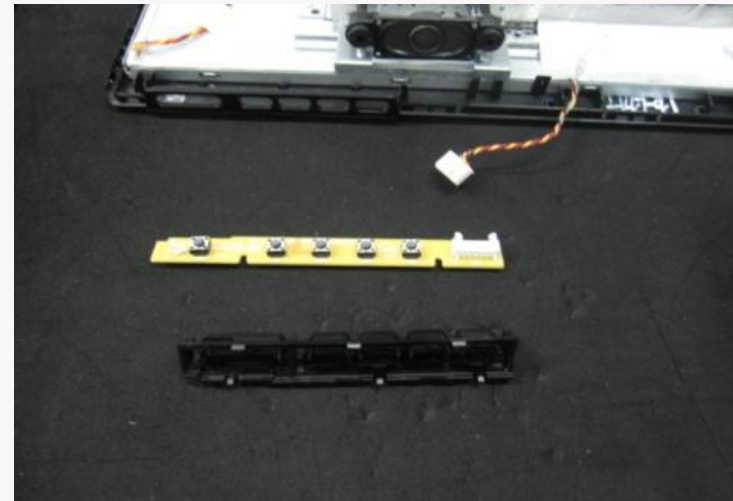
4. Remove Rear Cover.



Remove KEPC board From Front Cover



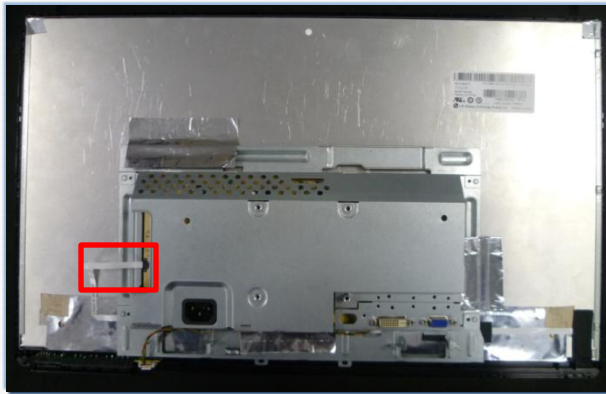
1. Take the KEPC assembly from the Front Cover.



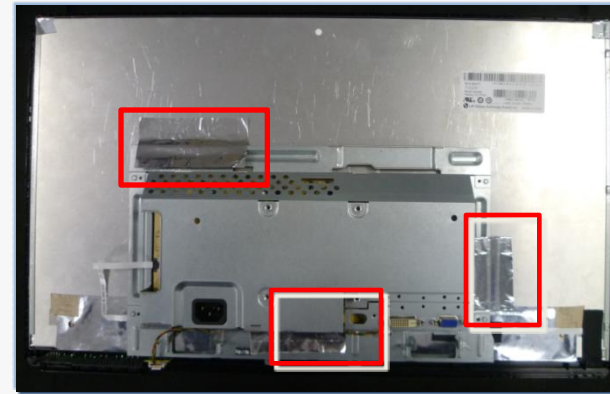
2. Remove Connector off from KEPC board and disassemble KEPC assembly .



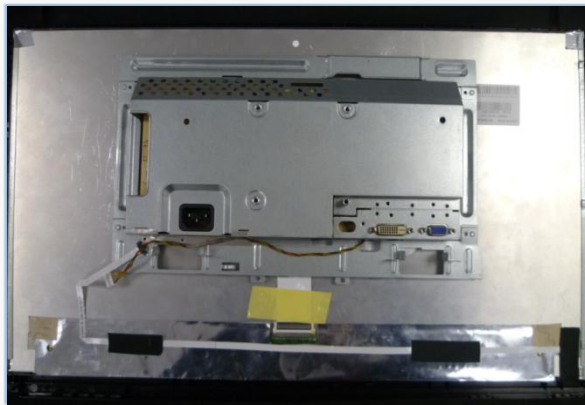
Remove Mainframe & Panel



1. Remove Connector off from Power board & Panel.



2. Remove the Conductive Tape from the Mainframe.



3. Remove Mainframe & Panel.



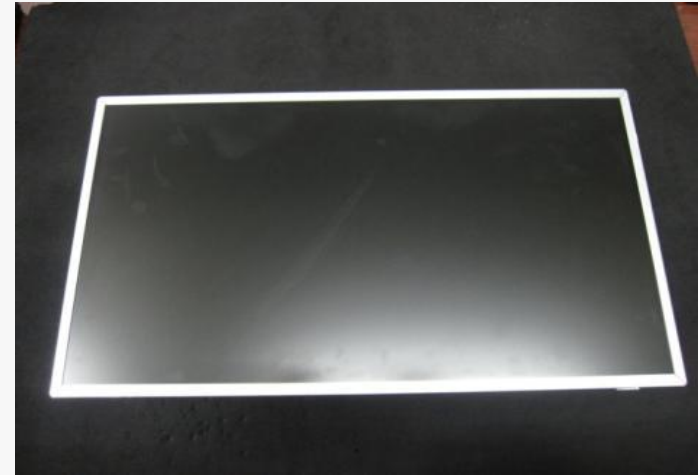
4. Remove the connecting wire



Remove Front Cover & Panel

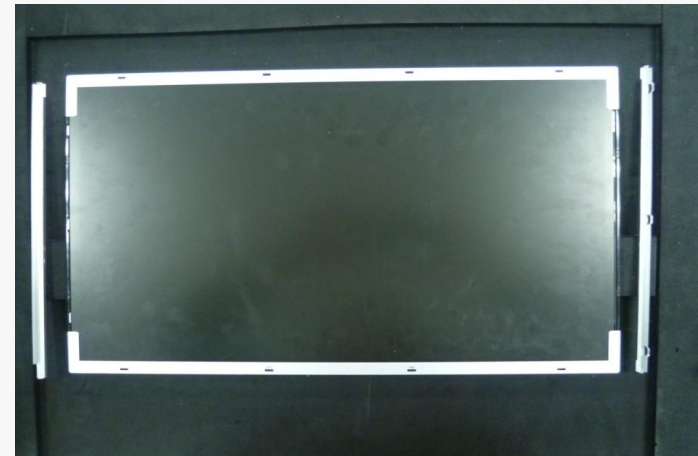
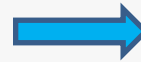


1. Turn over Panel, and remove the Front Cover off from Panel.



2. Dissecting to complete.

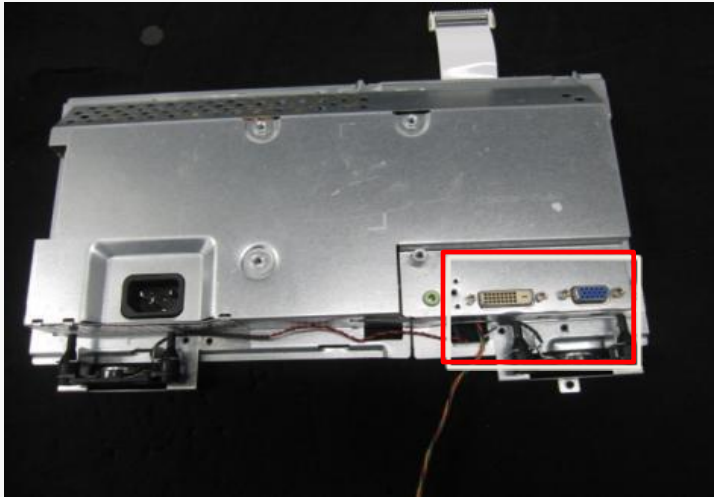
Direct at the LNT panel Modle



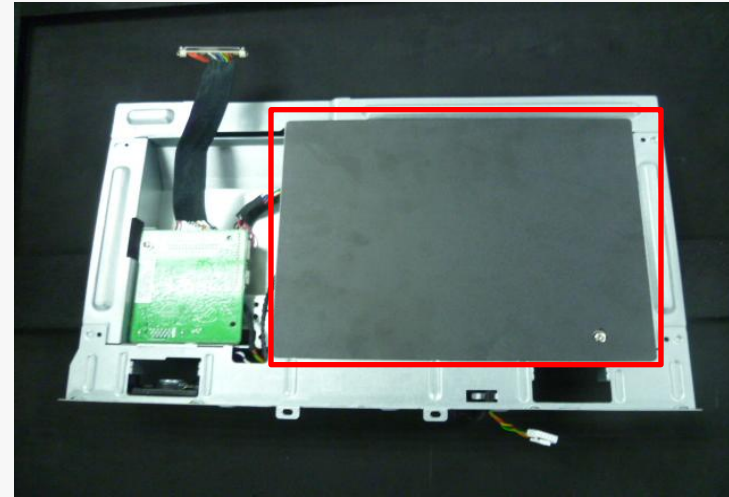
3. Demount BRACKET-L & BRACKET-R Form LNT panel.



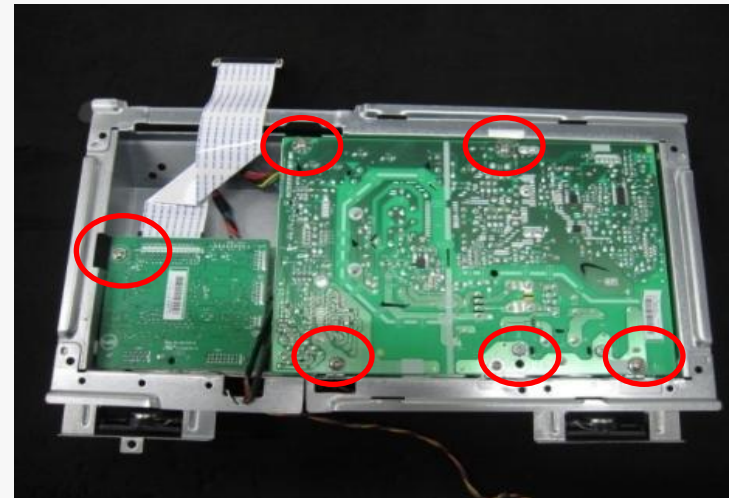
Take Screw off From Mainframe Assembly



1. Take Screw(*4 or 2) from Mainframe.



2. Tear off Mylar form mainframe

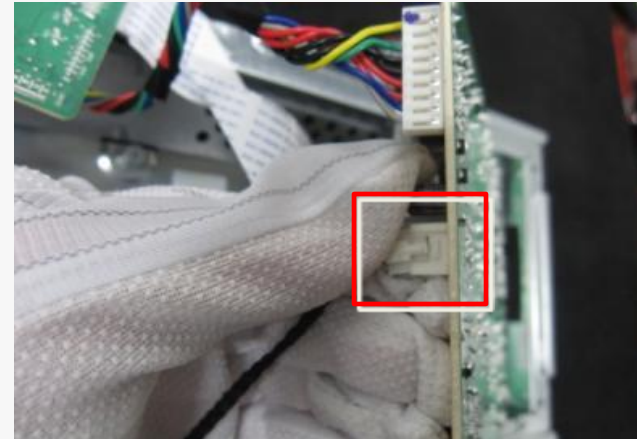


3. Take Screw(*6) from Power Bd & Main Bd .



Remove Mainframe & Barod

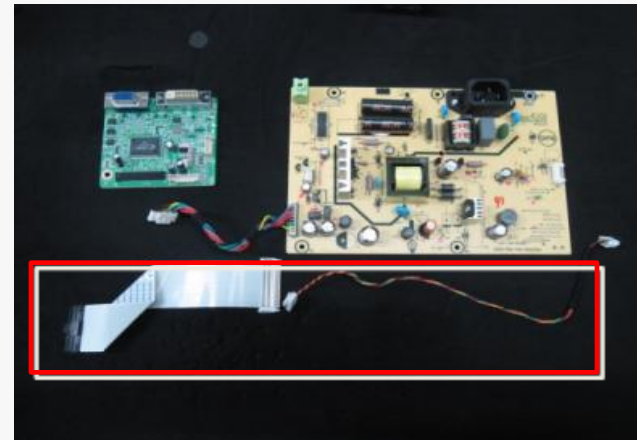
1. Direct at the Modle have Audio function:



Remove the Audio Connector off from Power Bd .



2.Remove the Power Bd & Main Bd off from Mainframe.

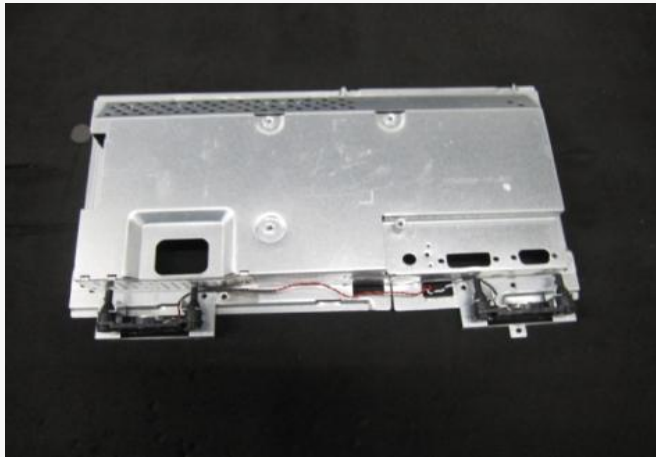


3.Remove the connecting wire off from Power Bd & Main Bd .

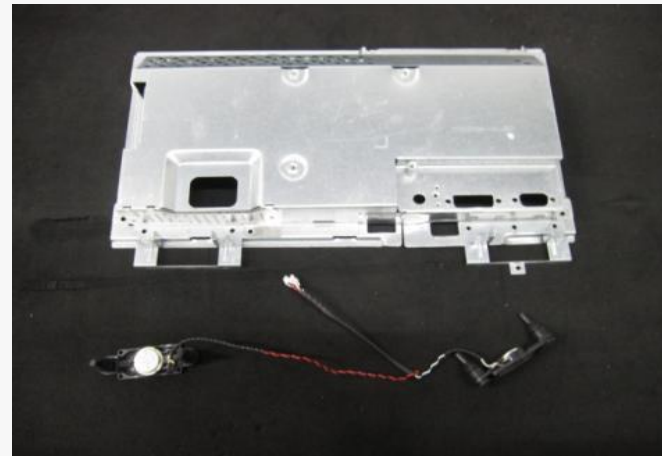


Remove Audio & Mainframe

Direct at the Modle have Audio function:



1. Take Mainframe, remove the Audio off from Mainframe.



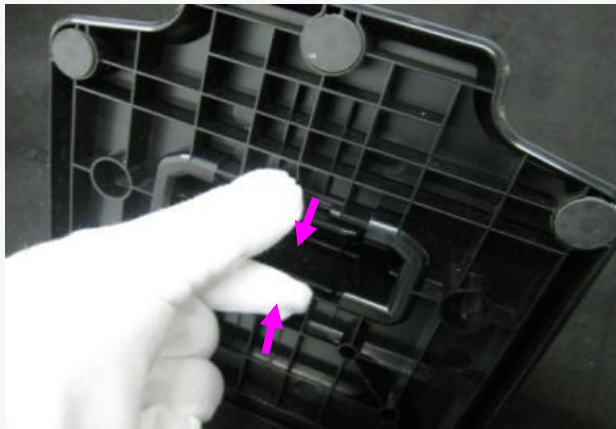
2. Dissecting to complete.



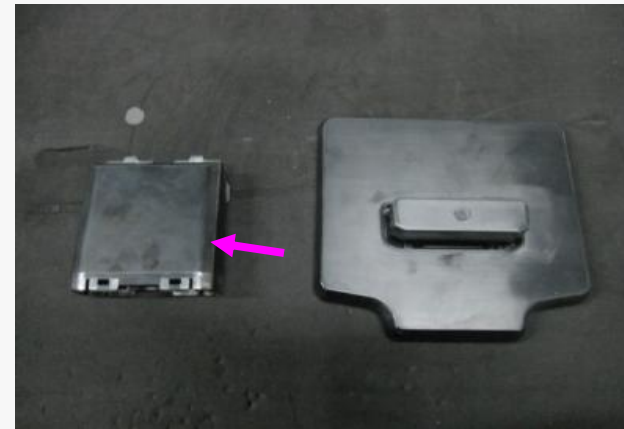
Remove Stand & Base



1. Take Stand assembly.



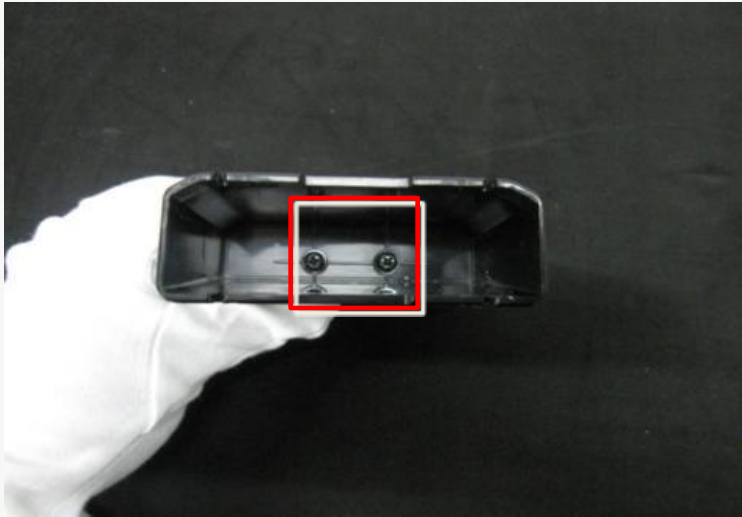
2. Pinch the limit RIB of Base.



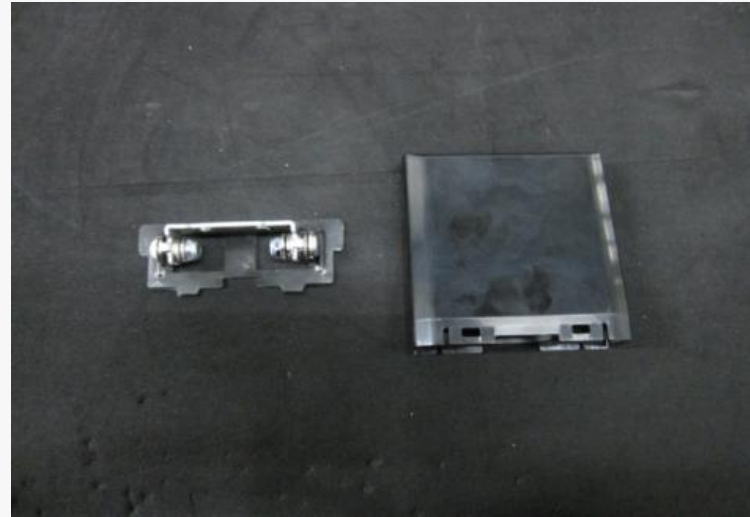
3. Remove the Stand off from the Base.



Remove hinge&stand



1. Take screw(*2) off, and remove the Hinge off from the Stand.



2. Dissecting to complete.



Thank You